Attorney Docket No. 55551-CIP (71360)

E UNITED STATES PATENT AND TRADEMARK OFFICE

APPLICANT:

Kanayama, et al.

EXAMINER: D.J. Buttner

SERIAL NO.:

09/768,931

GROUP:

1712

FILED:

January 24, 2001

FOR:

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USE

Assistant Commissioner for Patents

Washington, D.C. 20231

CERTIFICATE OF MAILING

I hereby certify that this paper (along with any paper referred to as being attached or enclosed) is being deposited with the United States Postal Service with sufficient postage as first class mail in an envelope addressed to the Commissioner of Patents and Trademarks, Washington, D.C. 20231 on August 23, 2002.

RESPONSE TO NOTICE OF NON-COMPLIANT AMENDMENT (37 CFR 1.121

Sir:

The following is in response to the Notice of Non-Compliant Amendment in response to an Iment submitted August 1, 2002, in the above referenced application.

Enclosed herewith for filing in the subject application are the following:

1. A copy of the Notice of Non-Compliant Amendment mailed August 16, 2002 Amendment submitted August 1, 2002, in the above referenced application.

- 2. Replacement page 2 of the Amendment submitted on August 1, 2002, which provides a clean version of the amended claims.

Applicants are in receipt of the Notice of Non-Compliant Amendment mailed August 16,

2002.